

## RTIS USE ONLY

Tracking Number 05914329  
Week Date 3/01/64  
FFW

a. Serial No.	f. Foreign Priority	k. Print Claim(s)	p. PTO-1449
b. Applicant(s)	g. Disclaimer	l. Print Fig.	q. PTOL-85b
c. Continuing Data	h. Microfiche Appendix	m. Searched Column	r. Abstract
d. PCT	i. Title	n. PTO-270/328	s. Sheets/Figs
e. Domestic Priority	j. Claims Allowed	o. PTO-892	t. Other

## MESSAGE

- a. Page Missing
- b. Text Continuity
- c. Holes through Data
- d. Other Missing Text
- e. Illegible Text
- f. Duplicate Text
- g. Brief Description
- h. Sequence Listing
- i. Appendix
- j. Amendments
- k. Other

- 1) On oath please verify country of last inventor Sadak Thambi Labeed.
- 2) Claim 27 (original 45) depends upon cancelled claim 44.
- 3) In examiner's amendment: in "claim 19, line 5" there is no "semiconductor die"  
See attached

Please advise  
Thank you  
PWC

## CLAIMS

- a. Claim(s) Missing
- b. Improper Dependency
- c. Duplicate Numbers
- d. Incorrect Numbering
- e. Index Disagrees
- f. Punctuation
- g. Amendments
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- k. Other

initials

## RESPONSE

initials

**DETAILED ACTION**

**EXAMINER'S AMENDMENT**

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

**AUTHORIZATION**

Authorization for this examiner's amendment was given in a telephone interview with Mr. Christopher J. Gaspar on February 6, 2004.

**TO CLAIMS**

Cancel claim 44. ✓

In claim 3, line 16, after semiconductor die, insert --wherein said attaching comprises attaching said thermal element to said conductive via--;

In claim 19, line 5, after semiconductor die, insert --wherein said attaching comprises attaching said thermal element to at least of said conductive via--;

In claim 52, line 5, after dissipating heat, insert --wherein said attaching comprises attaching said means for dissipating heat to said means for electrically connecting said first surface of said substrate with said second surface of said substrate--.

Also, cancel the non-elected claims 23-38. ✓

**Allowable Subject Matter**

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